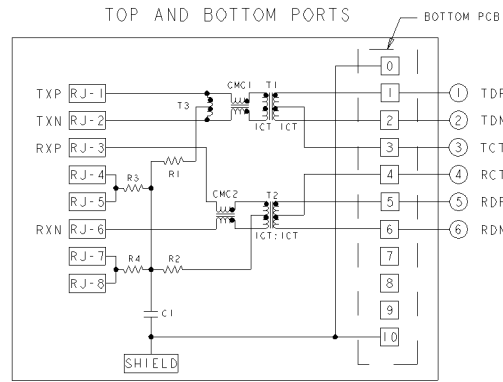
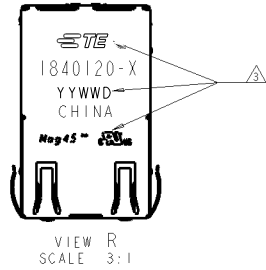


REV	DATE	REVISIONS	DATE	BY	APPD
AA	00				
A		NEW RELEASE		SANC2005	CS PD
B		ECO-08-022964		SANC2006	KD KL
C		ECO-11-019412		20080011	PP LJ

S814 MAGNETIC CIRCUIT STACKED



C1 = 1000pF, 24V, ±10%, X7R DECOUPLING CAP.
 R1-R4 = 75 OHMS, 1/16 W, ±5% RESISTORS

MATERIALS:
 PLASTIC HOUSING: BLACK, THERMOPLASTIC FLAMMABILITY RATING UL 94V-0
 SHIELD: BRASS, PLATED WITH 0.76 μm SEMI-BRIGHT NICKEL, POST DIPPED WITH 2.54 μm MIN SAC SOLDER ON SOLDER TAILS
 CONTACTS: PHOSPHOR BRONZE, 1.27 μm MIN OVERALL NICKEL UNDER PLATE WITH SELECT 1.27 μm MIN GOLD AT MATING INTERFACE AND 2.54 μm MIN MATTE TIN ON SOLDER TAILS.
 LED: DIFFUSED EPOXY LENS, CARBON STEEL LEAD FRAME
 LEADS: PREPLATED WITH 2.03 μm MIN SILVER OVER 1.02 μm MIN NICKEL UNDERPLATE OVER 1.02 μm MIN COPPER UNDERPLATE. POST-PLATED WITH 2.54 μm MIN MATTE TIN AND/OR SAC SOLDER DIP OR PURE TIN SOLDER DIP
 INTERNAL MAGNETICS PC BOARD: HIGH TEMP PCB, TG > 170°C

MAGNETICS
 APPLICATION: 10/100 BASE-T
 IMPEDANCE: 100 OHMS
 TURNS RATIO (CHIP: CABLE): TX = 1:1, RX = 1:1
 OPEN CIRCUIT INDUCTANCE (OCL): 350 μH MIN @ 100kHz, 0.1VRMS, 8mADC BIAS FROM 0°C TO 70°C, TX AND RX
 PERFORMANCE @ 25°C:
 INSERTION LOSS (IL): 1.1dB MAX FROM 0.5MHz TO 100MHz
 RETURN LOSS (RL): 18dB MIN FROM 0.5MHz TO 30MHz
 18-20LOG(f/30)dB MIN FROM 30.1MHz TO 60MHz
 12dB MIN FROM 60.1MHz TO 80MHz
 CROSSTALK ATTENUATION: 35dB MIN FROM 0.5MHz TO 40MHz
 33-20LOG(f/50)dB MIN FROM 40.1MHz TO 100MHz
 COMMON MODE REJECTION RATIO (CMRR): 30dB MIN FROM 0.5MHz TO 100MHz
 ISOLATION VOLTAGE: COMPLIES WITH IEEE802.3 2002, PARA 23.5.1.1, ITEM b.

TE CONNECTIVITY LOGO, PART NUMBER, DATE CODE, COUNTRY OF ORIGIN, AGENCY APPROVAL MARKING LOGO LOCATED IN THE APPROXIMATE AREA SHOWN. DATE CODE YY IS YEAR, WW IS WORK WEEK, D IS DAY OF WEEK, WITH SUNDAY=1

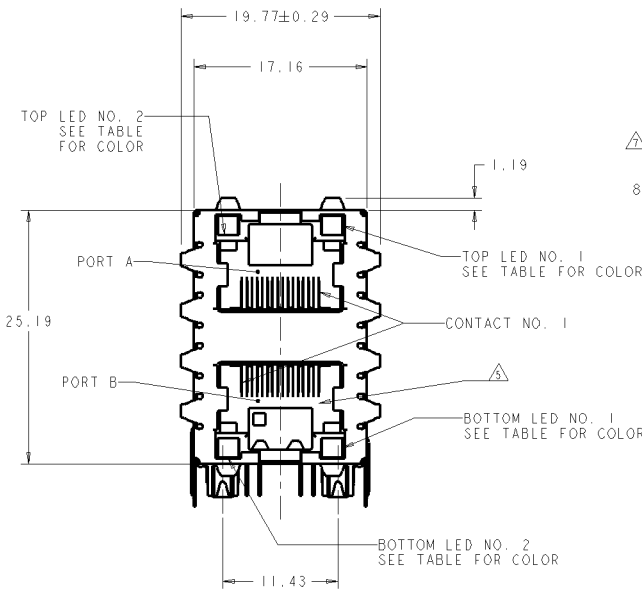
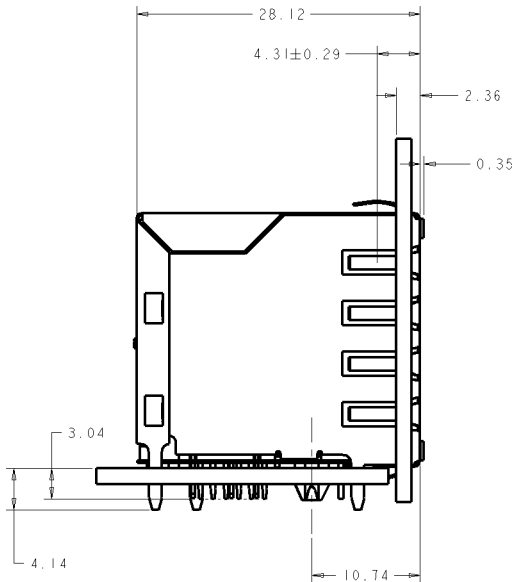
- OPERATING TEMPERATURE: FROM 0° C TO + 70° C.
- RJ45 CAVITY CONFORMS TO FCC RULES AND REGULATION PART 68 SUBPART F.
- LED'S COMPLIANT WITH IEC60825-1 SAFETY OF LASER PRODUCTS WHEN OPERATED AT CURRENT OF 20 mA MAX. LED IS DRIVEN WITH CONSTANT CURRENT AT APPROX 20mA. LED COLOR:

DOMINANT WAVELENGTH (λD): GREEN 568 nm TYP @ IF=20mA
 FORWARD VOLTAGE (VF): GREEN 2.2V TYP @ IF=20mA

DOMINANT WAVELENGTH (λD): YELLOW 588 nm TYP @ IF=20mA
 FORWARD VOLTAGE (VF): YELLOW 2.1V TYP @ IF=20mA

INDICATED CONNECTIONS ARE FOR NIC CONFIGURATION. THE MAGNETICS ARE ASYMMETRICAL AND DO NOT SUPPORT AUTO-MDI/MDIX.

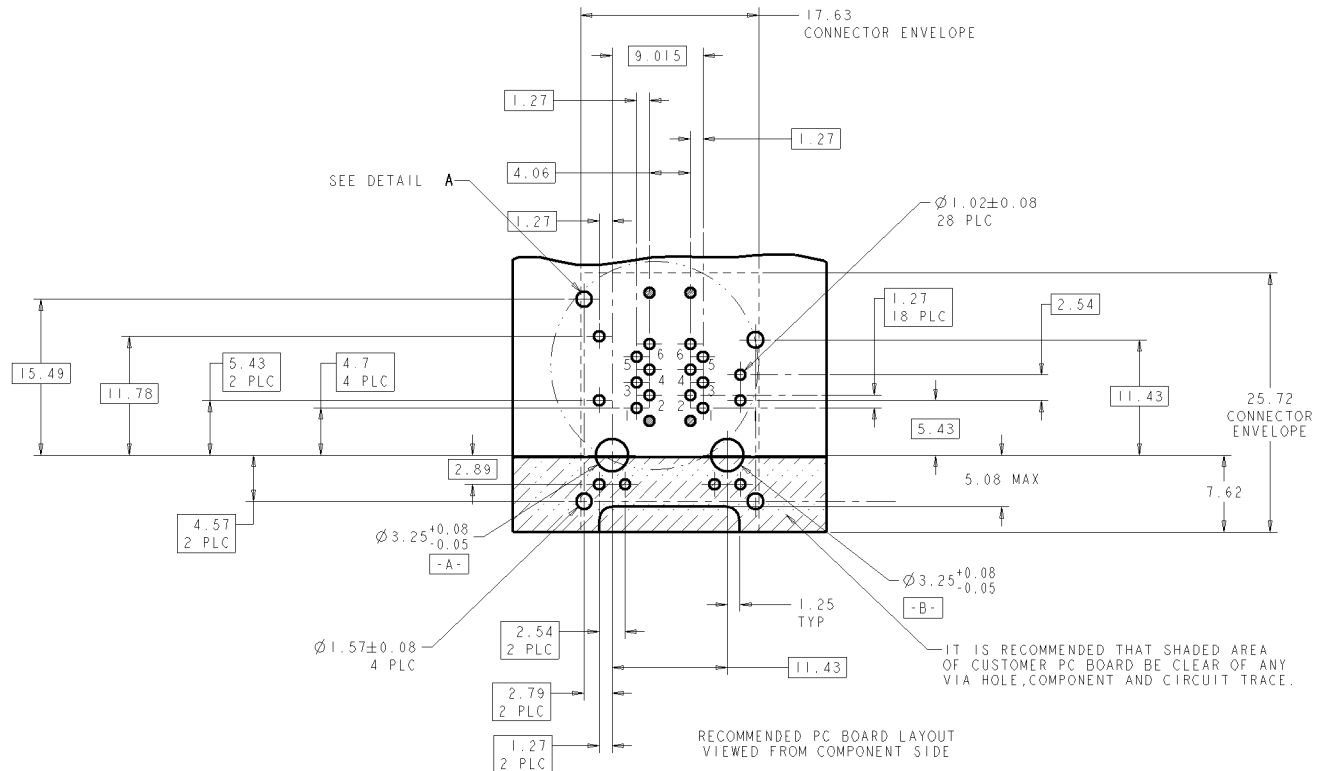
- THESE PARTS ARE RECOMMENDED FOR WAVE SOLDERING PROCESS. PEAK SOLDERING TEMPERATURE IS 260 °C MAX, 10 SECONDS MAX.



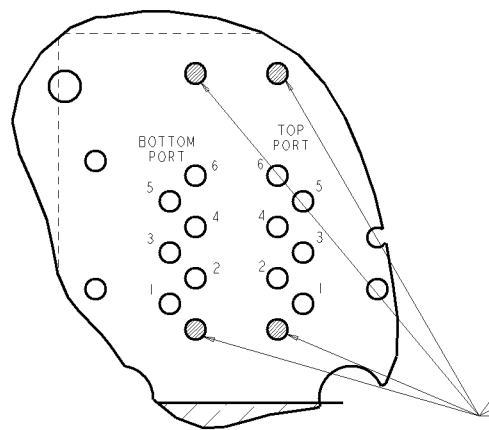
GRN/YEL	GRN/YEL	GRN/YEL	GRN/YEL	1840120-4
GREEN	YELLOW	GREEN	YELLOW	1840120-3
YELLOW	GREEN	GREEN	YELLOW	1840120-2
GREEN	GREEN	GREEN	GREEN	1840120-1
BOTTOM LED NO. 2	BOTTOM LED NO. 1	TOP LED NO. 2	TOP LED NO. 1	PART NO.

THIS DRAWING IS A CONTROLLED DOCUMENT		DESIGNED BY: G. GILLETTE	DATE: 03JAN2006	DRWING NO: 1840120-4
DRAWN BY: J. D'AMATO		DATE: 03JAN2006	DRWING NO: 1840120-4	REV: 1
CHECKED BY: J. FLICKINGER		DATE: 03JAN2006	DRWING NO: 1840120-4	REV: 1
APPROVED BY: J. FLICKINGER		DATE: 03JAN2006	DRWING NO: 1840120-4	REV: 1
MATERIAL: -		REVISION: -	DATE: 00779	REV: 1
CUSTOMER DRAWING		SHEET 1 OF 3		

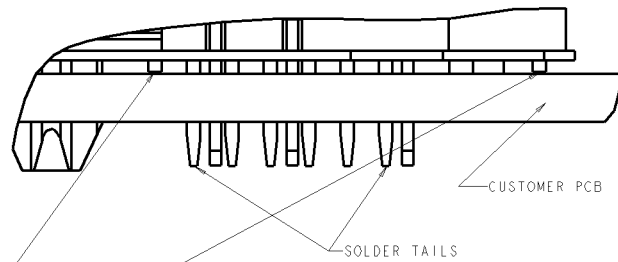
REV	DATE	DESCRIPTION	BY	CHKD	APPD
AA	00	SEE SHEET 1			



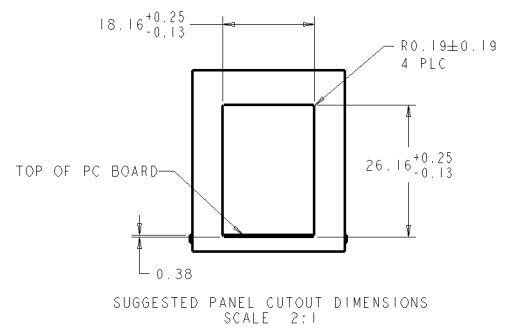
IT IS RECOMMENDED THAT SHADED AREA OF CUSTOMER PC BOARD BE CLEAR OF ANY VIA HOLE, COMPONENT AND CIRCUIT TRACE.



DETAIL A
 SCALE 8:1



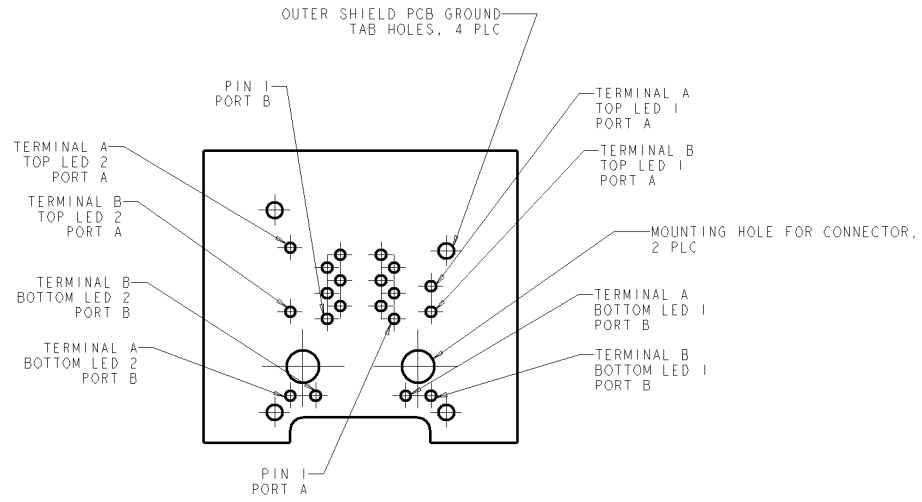
PIN #0 & PIN #10 ON MOD JACK ARE STUB PINS WITH LENGTH SIMILAR TO PCB STANDOFF HEIGHT. PRECAUTIONS SHOULD BE TAKEN IN PCB DESIGN TO GUARD AGAINST SHORTING TRACES TO STUB PINS.



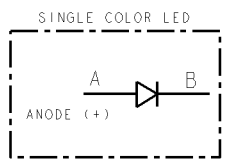
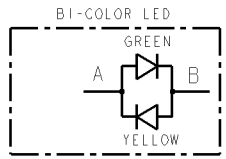
SUGGESTED PANEL CUTOUT DIMENSIONS
 SCALE 2:1

THIS DRAWING IS A CONTROLLED DOCUMENT		DESIGNED BY: G. GILLETTE CHECKED BY: D. AMATO DATE: 03 JAN 2016	DRAWN BY: J. FLICKINGER DATE: 03 JAN 2016	PRODUCT SPEC: 108-2100 APPLICATION SPEC:	SIZE: CASE CODE: DRAWING NO: 1840120 SHEET: 2 OF 3
DIMENSIONS: (mm) (INCHES) DIMENSIONS: (mm) (INCHES) DIMENSIONS: (mm) (INCHES) DIMENSIONS: (mm) (INCHES)	DIMENSIONS: (mm) (INCHES) DIMENSIONS: (mm) (INCHES) DIMENSIONS: (mm) (INCHES)	DIMENSIONS: (mm) (INCHES) DIMENSIONS: (mm) (INCHES) DIMENSIONS: (mm) (INCHES)	DIMENSIONS: (mm) (INCHES) DIMENSIONS: (mm) (INCHES) DIMENSIONS: (mm) (INCHES)	DIMENSIONS: (mm) (INCHES) DIMENSIONS: (mm) (INCHES) DIMENSIONS: (mm) (INCHES)	DIMENSIONS: (mm) (INCHES) DIMENSIONS: (mm) (INCHES) DIMENSIONS: (mm) (INCHES)

REV	DATE	DESCRIPTION	DATE	BY	APP
AA	00	7-1	LYF	-	-
		-	-	SEE SHEET 1	-



LED HOLE DESIGNATIONS VIEWED FROM COMPONENT SIDE
 SCALE 4:1



THIS DRAWING IS A CONTROLLED DOCUMENT		DESIGNED BY: J. GILLETTE DATE: 03JAN2006 CHECKED BY: P. D'AMATO DATE: 03JAN2006 DRAWN BY: P. FLICKINGER DATE: 03JAN2006	INTEGRATED MAGNETIC STACKED MODULAR JACK, 2X1 W/LEDS, 10/100 ETHERNET, RJ45, GROUND SHIELD, HT PCB
DIMENSIONS: mm (INCHES) DIMENSIONS: 0.000125 (0.005)	DIMENSIONS: 0.000125 (0.005) DIMENSIONS: 0.000125 (0.005) DIMENSIONS: 0.000125 (0.005) DIMENSIONS: 0.000125 (0.005)	PRODUCT SPEC: 108-2100 APPLICATION SPEC:	SIZE: CASE CODE: DRAWING NO: 40 REV: A 00779 © 1840120 SHEETS: 3 OF 3 REV: C
MATERIAL: UNLESS OTHERWISE SPECIFIED		CUSTOMER DRAWING	DATE: N/A